

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5498296

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HAO YIN	04/19/2019
DAN SHI	04/19/2019
XIYAO LIU	04/19/2019
DONGQUAN LIU	04/19/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SASET CHENGDU TECHNOLOGY LTD.
<b>Street Address:</b>	NO. 5 GAOPENG AVENUE HIGH-TECH ZONE
<b>Internal Address:</b>	SICHUAN
<b>City:</b>	CHENGDU
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	610041
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16346079
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(559)840-0856
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	5598400841
<b>Email:</b>	drewfortney@cencalip.com
<b>Correspondent Name:</b>	CENTRAL CALIFORNIA IP GROUP, P.C.
<b>Address Line 1:</b>	377 W. FALLBROOK AVE., SUITE 205
<b>Address Line 4:</b>	FRESNO, CALIFORNIA 93711
<b>ATTORNEY DOCKET NUMBER:</b>	SCLJ-036-US
<b>NAME OF SUBMITTER:</b>	ANDREW D. FORTNEY, PH.D., REG. NO. 34600
<b>SIGNATURE:</b>	/Andrew D. Fortney/
<b>DATE SIGNED:</b>	04/29/2019
<b>Total Attachments: 2</b>	
source=SCLJ-036-US_Assignment4Filing_20190429_#page1.tif	



ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned,

Hao YIN

Dan SHI

Xiyao LIU

Dongquan LIU

who have created a certain invention for which an application for United States Letters Patent was executed by me concurrently herewith and entitled:

**QUANTITATIVE SHEAR WAVE ELASTICITY IMAGING METHOD AND SYSTEM**


Do hereby sell, assign and transfer to SASET CHENGDU TECHNOLOGY LTD., a corporation of the People's Republic of China, having a place of business at No. 5 Gaopeng Avenue High-tech Zone, Chengdu, Sichuan 610041 China

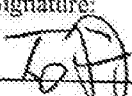
its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;


Agree that SASET CHENGDU TECHNOLOGY LTD., hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

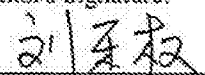
Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below.

Full Name of Sole/First Inventor: <b>Hao YIN</b>	
Inventor's Signature: 	Date: Month/Day/Year 4/19/2019

Full Name of Second Inventor, if any: <b>Dan SHI</b>	
Inventor's Signature: 	Date: Month/Day/Year 4/19/2019

Full Name of Third Inventor, if any: <b>Xiyao LIU</b>	
Inventor's Signature: 	Date: Month/Day/Year 4/19/2019

Full Name of Fourth Inventor, if any: <b>Dongquan LIU</b>	
Inventor's Signature: 	Date: Month/Day/Year 4/19/2019

Full Name of Fifth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Sixth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Seventh Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Eighth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Full Name of Ninth Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year